

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An optical module comprising:  
an optical subassembly including a semiconductor optical device therein, the optical subassembly having a co-axial shape;  
~~a housing including a base and a cover, the base having a bottom surface, and the optical subassembly being provided between the base and the cover;~~  
a support including first and second leg portions and a bridge connecting the first and second leg portions, the first and second leg portions securing the optical subassembly therebetween by being in contact with the optical subassembly, ~~the support being disposed on the bottom surface of the base; and;~~  
a housing including a base and a cover, the base having a bottom surface for providing the optical subassembly and the first and second leg portions of the support thereon; and  
a thermal sheet provided between the cover and the support,  
wherein the support reduces a stress applied to the optical subassembly from the cover through the thermal sheet and provides forms a thermal path from the optical subassembly to the cover.

2. (Cancelled)

3. (Cancelled)

4. (Currently Amended) The optical module according to claim 1, wherein the optical subassembly has ~~an outer surface and includes~~ a stem for mounting the semiconductor optical device thereon, and

~~wherein the support further includes a first leg portion, a second leg portion, a bridge connecting the first and second leg portions with each other, and a finger curved to be in contact with the outer surface of the stem, the first and second leg portions providing the optical subassembly therebetween, and the thermal sheet being provided between the bridge and the cover.~~

5. (Original) The optical module according to claim 4, wherein the outer surface of the optical subassembly is spaced from the bridge.

6. (Original) The optical module according to claim 4, wherein the finger is in contact with the stem with a solder provided between the stem and the finger.

7. (Withdrawn) The optical module according to claim 4, wherein the support has another bridge for securing the finger with the first and second leg portions.

8. (Withdrawn) The optical module according to claim 7, wherein a level of the bridge relative to the bottom surface of the base is greater than a level of the other bridge relative to the bottom surface of the base.

9. (Withdrawn) The optical module according to claim 7, wherein the other bridge is spaced from the outer surface of the stem.

10. (Withdrawn) The optical module according to claim 7, wherein the support further includes first and second arms provided on sides of the first and second leg portions for connecting the other bridge to the first and second leg portions, the first and second arms being connected with each other by the other bridge.

11. (Withdrawn) The optical module according to claim 10, wherein the other bridge has an inner side facing to the bridge, the finger being provided on the inner side.

12. (Withdrawn) The optical module according to claim 11, further comprising a circuit board provided in the housing,

wherein the optical subassembly has a lead terminal, connected to the circuit board.